

RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



XKB Connectivity

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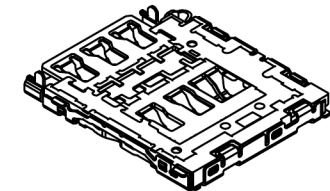
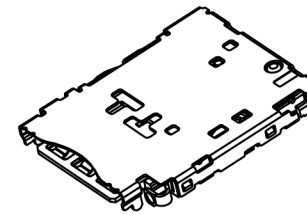
NOTE:

- 材料 Material:
 - 1-1 胶壳 Housing: High Temperature Thermoplastic(LCP)Color Black UL 94V-0
 - 1-2 触点 Contact: Phosphor Bronze(C5210)
 - 1-3 盖子 Cover: Stainless steel
- 电镀 Plating:
 - 2-1 接触端子 Contact terminal:
 - 接触电阻 Contact area: Gold 1u" Min.
 - 焊料区 Solder area: Gold 0.8u" Min
 - 底镀 Underplating: Ni overall 50u" Min
 - 2-2 盖子 Cover:
 - 底镀 Underplating: Ni overall 30u" Min.
 - 焊料区 Solder area: Gold 0.8u" Min .
- 规格 Specification:
 - 3-1. 额定电流 Current Rating :0.5A max.
 - 3-2. 接触电阻 Contact Resistance: 50 mOhms max
 - 3-3. 绝缘电阻 Insulation Resistance : 1000 MOhms min./500VDC
 - 3-4. 介电耐受电压 Dielectric Withstanding Voltage: 50 V AC/1minute
 - 3-5. 工作温度 Operating Temperature: -25°C to +85°C
 - 3-6. 寿命 Mating Cycles: 5000 Insertions
- Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC

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SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



广东星坤科技股份有限公司

DATE:
 日期:
 生效日期:
 日期:

MARK:
 文件工程章

REVISIONS

www.xk-dg.cn www.helloxkb.com www.helloxkb.cn

UNSPECIFIED TOLERANCES

DSND		DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
DWN		DATE	VIEW:	PART NO.:
CHKD		DATE	UNIT: mm/in	DWG NO.:
APPD		DATE	SIZE: A4	XK NANO-1131-04
XKB INDUSTRIAL PRECISION CO., LIMITED				WEIGHT
				1.0g
				SHEET
				1/1
				REVISION
				A0